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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Not For New Designs
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I ² C, LINbus, SIO, SSU, UART/USART
Peripherals	POR, PWM, Voltage Detect, WDT
Number of I/O	59
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	2.5K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 12x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LFQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f21366cnfp-30

1.1.2 Specifications

Tables 1.1 and 1.2 outline the Specifications for R8C/36C Group.

Table 1.1 Specifications for R8C/36C Group (1)

Item	Function	Specification
CPU	Central processing unit	R8C CPU core <ul style="list-style-type: none"> • Number of fundamental instructions: 89 • Minimum instruction execution time: <ul style="list-style-type: none"> 50 ns ($f(XIN) = 20$ MHz, $VCC = 2.7$ to 5.5 V) 200 ns ($f(XIN) = 5$ MHz, $VCC = 1.8$ to 5.5 V) • Multiplier: 16 bits \times 16 bits \rightarrow 32 bits • Multiply-accumulate instruction: 16 bits \times 16 bits + 32 bits \rightarrow 32 bits • Operation mode: Single-chip mode (address space: 1 Mbyte)
Memory	ROM, RAM, Data flash	Refer to Table 1.3 Product List for R8C/36C Group
Power Supply Voltage Detection	Voltage detection circuit	<ul style="list-style-type: none"> • Power-on reset • Voltage detection 3 (detection level of voltage detection 0 and voltage detection 1 selectable)
I/O Ports	Programmable I/O ports	<ul style="list-style-type: none"> • Input-only: 1 pin • CMOS I/O ports: 59, selectable pull-up resistor • High current drive ports: 59
Clock	Clock generation circuits	<ul style="list-style-type: none"> • 4 circuits: XIN clock oscillation circuit, XCIN clock oscillation circuit (32 kHz), High-speed on-chip oscillator (with frequency adjustment function), Low-speed on-chip oscillator • Oscillation stop detection: XIN clock oscillation stop detection function • Frequency divider circuit: Dividing selectable 1, 2, 4, 8, and 16 • Low power consumption modes: <ul style="list-style-type: none"> Standard operating mode (high-speed clock, low-speed clock, high-speed on-chip oscillator, low-speed on-chip oscillator), wait mode, stop mode
		Real-time clock (timer RE)
Interrupts		<ul style="list-style-type: none"> • Interrupt Vectors: 69 • External: 9 sources ($\overline{INT} \times 5$, key input $\times 4$) • Priority levels: 7 levels
Watchdog Timer		<ul style="list-style-type: none"> • 14 bits \times 1 (with prescaler) • Reset start selectable • Low-speed on-chip oscillator for watchdog timer selectable
DTC (Data Transfer Controller)		<ul style="list-style-type: none"> • 1 channel • Activation sources: 39 • Transfer modes: 2 (normal mode, repeat mode)
Timer	Timer RA	8 bits \times 1 (with 8-bit prescaler) Timer mode (period timer), pulse output mode (output level inverted every period), event counter mode, pulse width measurement mode, pulse period measurement mode
	Timer RB	8 bits \times 1 (with 8-bit prescaler) Timer mode (period timer), programmable waveform generation mode (PWM output), programmable one-shot generation mode, programmable wait one-shot generation mode
	Timer RC	16 bits \times 1 (with 4 capture/compare registers) Timer mode (input capture function, output compare function), PWM mode (output 3 pins), PWM2 mode (PWM output pin)
	Timer RD	16 bits \times 2 (with 4 capture/compare registers) Timer mode (input capture function, output compare function), PWM mode (output 6 pins), reset synchronous PWM mode (output three-phase waveforms (6 pins), sawtooth wave modulation), complementary PWM mode (output three-phase waveforms (6 pins), triangular wave modulation), PWM3 mode (PWM output 2 pins with fixed period)

Table 1.2 Specifications for R8C/36C Group (2)

Item	Function	Specification
Timer	Timer RE	8 bits × 1 Real-time clock mode (count seconds, minutes, hours, days of week), output compare mode
	Timer RF	16 bits × 1 Input capture mode (input capture circuit), output compare mode (output compare circuit)
	Timer RG	16 bits × 1 (with 2 capture/compare registers) Timer mode (input capture function, output compare function), PWM mode (output 1 pin), phase counting mode (available automatic measurement for the counts of 2-phase encoder)
Serial Interface	UART0, UART1	Clock synchronous serial I/O/UART × 2 channel
	UART2	Clock synchronous serial I/O, UART, I ² C mode (I ² C bus), multiprocessor communication function
Synchronous Serial Communication Unit (SSU)		1 (shared with I ² C bus)
I ² C bus		1 (shared with SSU)
LIN Module		Hardware LIN: 1 (timer RA, UART0)
A/D Converter		10-bit resolution × 12 channels, includes sample and hold function, with sweep mode
D/A Converter		8-bit resolution × 2 circuits
Comparator B		2 circuits
Flash Memory		<ul style="list-style-type: none"> • Programming and erasure voltage: VCC = 2.7 to 5.5 V • Programming and erasure endurance: 10,000 times (data flash), 1,000 times (program ROM) • Program security: ROM code protect, ID code check • Debug functions: On-chip debug, on-board flash rewrite function • Background operation (BGO) function (data flash)
Operating Frequency/Supply Voltage		f(XIN) = 20 MHz (VCC = 2.7 to 5.5 V) f(XIN) = 5 MHz (VCC = 1.8 to 5.5 V)
Current consumption		Typ. 7.0 mA (VCC = 5.0 V, f(XIN) = 20 MHz) Typ. 3.5 mA (VCC = 3.0 V, f(XIN) = 10 MHz) Typ. 4.0 μA (VCC = 3.0 V, wait mode (f(XCIN) = 32 kHz)) Typ. 2.0 μA (VCC = 3.0 V, stop mode)
Operating Ambient Temperature		−20 to 85°C (N version) −40 to 85°C (D version) ⁽¹⁾
Package		64-pin LQFP <ul style="list-style-type: none"> • Package code: PLQP0064KB-A (previous code: 64P6Q-A) • Package code: PLQP0064GA-A (previous code: 64P6U-A) 64-pin TQFP <ul style="list-style-type: none"> • Package code: PTQP0064LB-A

Note:

1. Specify the D version if D version functions are to be used.

1.2 Product List

Tables 1.3 and 1.4 list Product List for R8C/36C Group. Figure 1.1 shows a Part Number, Memory Size, and Package of R8C/36C Group.

Table 1.3 Product List for R8C/36C Group (1)

Current of Nov 2010

Part No.	ROM Capacity		RAM Capacity	Package Type	Remarks	
	Program ROM	Data flash				
R5F21364CNFP	16 Kbytes	1 Kbyte × 4	1.5 Kbytes	PLQP0064KB-A	N version	
R5F21365CNFP	24 Kbytes	1 Kbyte × 4	2 Kbytes	PLQP0064KB-A		
R5F21366CNFP	32 Kbytes	1 Kbyte × 4	2.5 Kbytes	PLQP0064KB-A		
R5F21367CNFP	48 Kbytes	1 Kbyte × 4	4 Kbytes	PLQP0064KB-A		
R5F21368CNFP	64 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0064KB-A		
R5F2136ACNFP	96 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0064KB-A		
R5F2136CCNFP	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0064KB-A		
R5F21364CNFA	16 Kbytes	1 Kbyte × 4	1.5 Kbytes	PLQP0064GA-A		
R5F21365CNFA	24 Kbytes	1 Kbyte × 4	2 Kbytes	PLQP0064GA-A		
R5F21366CNFA	32 Kbytes	1 Kbyte × 4	2.5 Kbytes	PLQP0064GA-A		
R5F21367CNFA	48 Kbytes	1 Kbyte × 4	4 Kbytes	PLQP0064GA-A		
R5F21368CNFA	64 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0064GA-A		
R5F2136ACNFA	96 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0064GA-A		
R5F2136CCNFA	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0064GA-A		
R5F21364CNFB (D)	16 Kbytes	1 Kbyte × 4	1.5 Kbytes	PTQP0064LB-A		
R5F21365CNFB (D)	24 Kbytes	1 Kbyte × 4	2 Kbytes	PTQP0064LB-A		
R5F21366CNFB (D)	32 Kbytes	1 Kbyte × 4	2.5 Kbytes	PTQP0064LB-A		
R5F21367CNFB (D)	48 Kbytes	1 Kbyte × 4	4 Kbytes	PTQP0064LB-A		
R5F21368CNFB (D)	64 Kbytes	1 Kbyte × 4	6 Kbytes	PTQP0064LB-A		
R5F2136ACNFB (D)	96 Kbytes	1 Kbyte × 4	8 Kbytes	PTQP0064LB-A		
R5F2136CCNFB (D)	128 Kbytes	1 Kbyte × 4	10 Kbytes	PTQP0064LB-A		
R5F21364CNXXXFP	16 Kbytes	1 Kbyte × 4	1.5 Kbytes	PLQP0064KB-A	N version Factory programming product (1)	
R5F21365CNXXXFP	24 Kbytes	1 Kbyte × 4	2 Kbytes	PLQP0064KB-A		
R5F21366CNXXXFP	32 Kbytes	1 Kbyte × 4	2.5 Kbytes	PLQP0064KB-A		
R5F21367CNXXXFP	48 Kbytes	1 Kbyte × 4	4 Kbytes	PLQP0064KB-A		
R5F21368CNXXXFP	64 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0064KB-A		
R5F2136ACNXXXFP	96 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0064KB-A		
R5F2136CCNXXXFP	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0064KB-A		
R5F21364CNXXXFA	16 Kbytes	1 Kbyte × 4	1.5 Kbytes	PLQP0064GA-A		
R5F21365CNXXXFA	24 Kbytes	1 Kbyte × 4	2 Kbytes	PLQP0064GA-A		
R5F21366CNXXXFA	32 Kbytes	1 Kbyte × 4	2.5 Kbytes	PLQP0064GA-A		
R5F21367CNXXXFA	48 Kbytes	1 Kbyte × 4	4 Kbytes	PLQP0064GA-A		
R5F21368CNXXXFA	64 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0064GA-A		
R5F2136ACNXXXFA	96 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0064GA-A		
R5F2136CCNXXXFA	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0064GA-A		
R5F21364CNXXXFB (D)	16 Kbytes	1 Kbyte × 4	1.5 Kbytes	PTQP0064LB-A		
R5F21365CNXXXFB (D)	24 Kbytes	1 Kbyte × 4	2 Kbytes	PTQP0064LB-A		
R5F21366CNXXXFB (D)	32 Kbytes	1 Kbyte × 4	2.5 Kbytes	PTQP0064LB-A		
R5F21367CNXXXFB (D)	48 Kbytes	1 Kbyte × 4	4 Kbytes	PTQP0064LB-A		
R5F21368CNXXXFB (D)	64 Kbytes	1 Kbyte × 4	6 Kbytes	PTQP0064LB-A		
R5F2136ACNXXXFB (D)	96 Kbytes	1 Kbyte × 4	8 Kbytes	PTQP0064LB-A		
R5F2136CCNXXXFB (D)	128 Kbytes	1 Kbyte × 4	10 Kbytes	PTQP0064LB-A		

(D): Under development

Note:

1. The user ROM is programmed before shipment.

2. Central Processing Unit (CPU)

Figure 2.1 shows the CPU Registers. The CPU contains 13 registers. R0, R1, R2, R3, A0, A1, and FB configure a register bank. There are two sets of register bank.

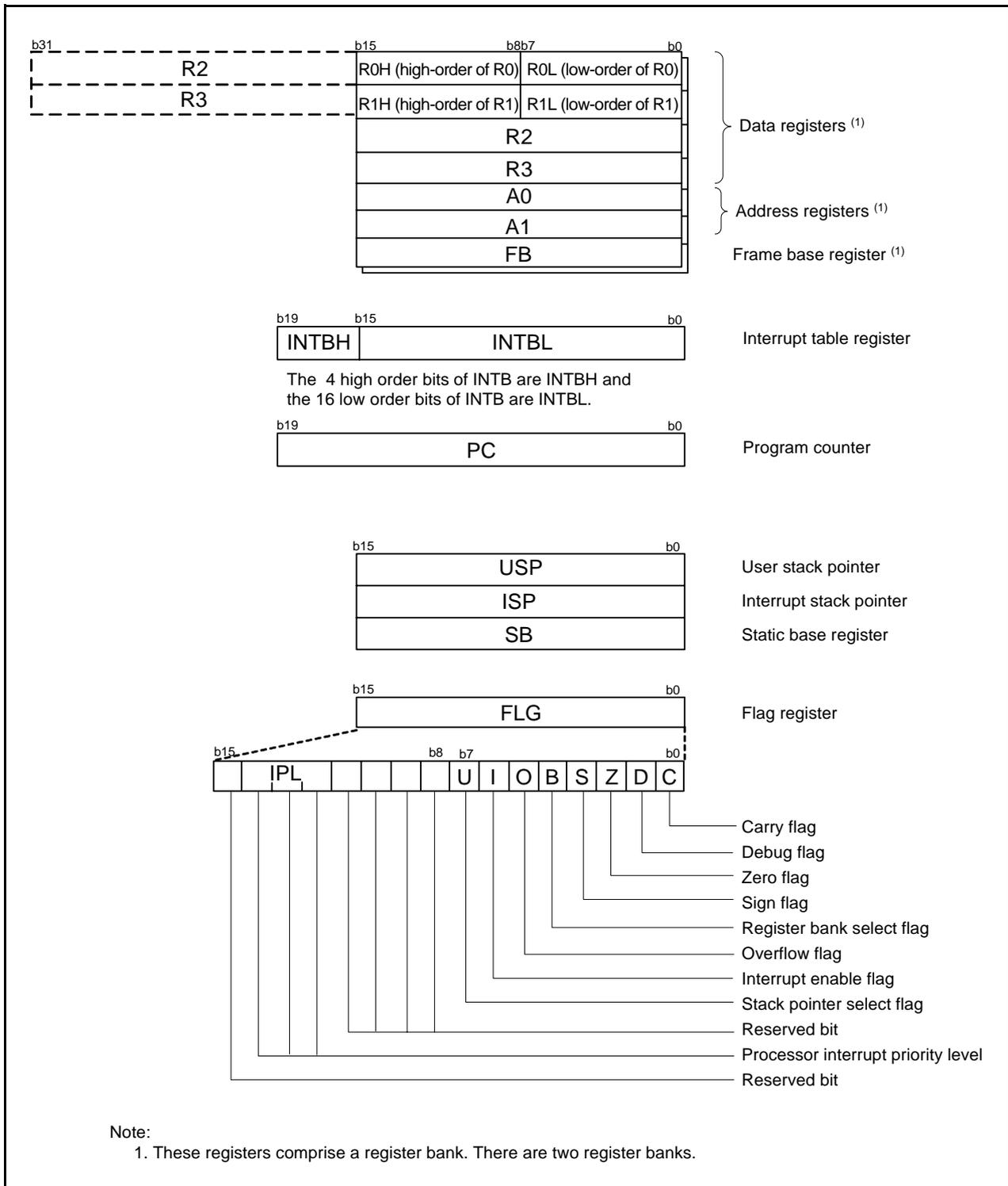


Figure 2.1 CPU Registers

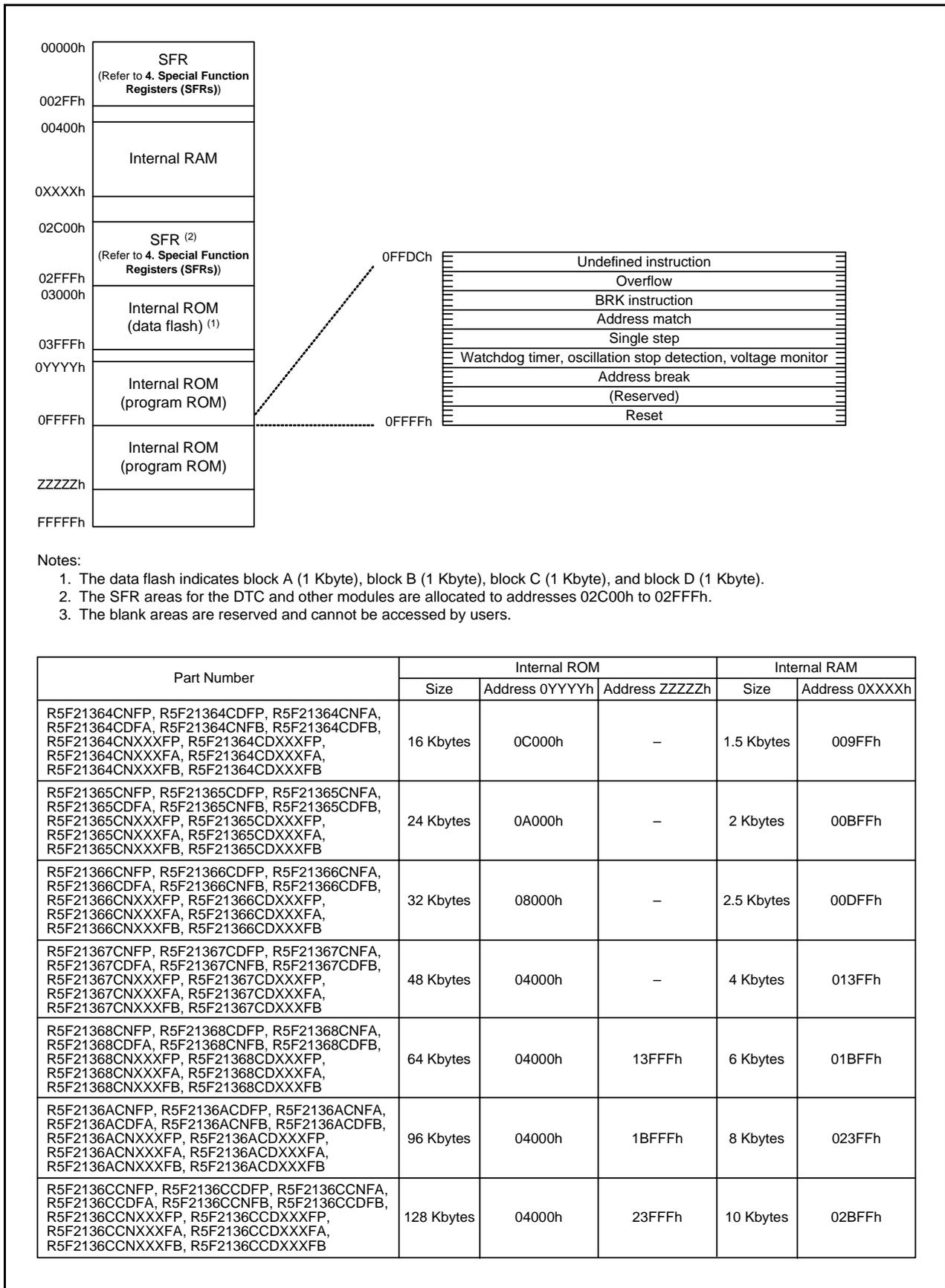


Figure 3.1 Memory Map of R8C/36C Group

Table 4.4 SFR Information (4) (1)

Address	Register	Symbol	After Reset
00C0h	A/D Register 0	AD0	XXh
00C1h			000000XXb
00C2h	A/D Register 1	AD1	XXh
00C3h			000000XXb
00C4h	A/D Register 2	AD2	XXh
00C5h			000000XXb
00C6h	A/D Register 3	AD3	XXh
00C7h			000000XXb
00C8h	A/D Register 4	AD4	XXh
00C9h			000000XXb
00CAh	A/D Register 5	AD5	XXh
00CBh			000000XXb
00CCh	A/D Register 6	AD6	XXh
00CDh			000000XXb
00CEh	A/D Register 7	AD7	XXh
00CFh			000000XXb
00D0h			
00D1h			
00D2h			
00D3h			
00D4h	A/D Mode Register	ADMOD	00h
00D5h	A/D Input Select Register	ADINSEL	11000000b
00D6h	A/D Control Register 0	ADCON0	00h
00D7h	A/D Control Register 1	ADCON1	00h
00D8h	D/A0 Register	DA0	00h
00D9h	D/A1 Register	DA1	00h
00DAh			
00DBh			
00DCh	D/A Control Register	DACON	00h
00DDh			
00DEh			
00DFh			
00E0h	Port P0 Register	P0	XXh
00E1h	Port P1 Register	P1	XXh
00E2h	Port P0 Direction Register	PD0	00h
00E3h	Port P1 Direction Register	PD1	00h
00E4h	Port P2 Register	P2	XXh
00E5h	Port P3 Register	P3	XXh
00E6h	Port P2 Direction Register	PD2	00h
00E7h	Port P3 Direction Register	PD3	00h
00E8h	Port P4 Register	P4	XXh
00E9h	Port P5 Register	P5	XXh
00EAh	Port P4 Direction Register	PD4	00h
00EBh	Port P5 Direction Register	PD5	00h
00ECh	Port P6 Register	P6	XXh
00EDh			
00EEh	Port P6 Direction Register	PD6	00h
00EFh			
00F0h	Port P8 Register	P8	XXh
00F1h			
00F2h	Port P8 Direction Register	PD8	00h
00F3h			
00F4h			
00F5h			
00F6h			
00F7h			
00F8h			
00F9h			
00FAh			
00FBh			
00FCh			
00FDh			
00FEh			
00FFh			

X: Undefined

Note:

1. The blank areas are reserved and cannot be accessed by users.

Table 4.6 SFR Information (6) (1)

Address	Register	Symbol	After Reset
0140h	Timer RD Control Register 0	TRDCR0	00h
0141h	Timer RD I/O Control Register A0	TRDIORA0	10001000b
0142h	Timer RD I/O Control Register C0	TRDIORC0	10001000b
0143h	Timer RD Status Register 0	TRDSR0	11100000b
0144h	Timer RD Interrupt Enable Register 0	TRDIER0	11100000b
0145h	Timer RD PWM Mode Output Level Control Register 0	TRDPOCR0	11111000b
0146h	Timer RD Counter 0	TRD0	00h
0147h			00h
0148h	Timer RD General Register A0	TRDGRA0	FFh
0149h			FFh
014Ah	Timer RD General Register B0	TRDGRB0	FFh
014Bh			FFh
014Ch	Timer RD General Register C0	TRDGRC0	FFh
014Dh			FFh
014Eh	Timer RD General Register D0	TRDGRD0	FFh
014Fh			FFh
0150h	Timer RD Control Register 1	TRDCR1	00h
0151h	Timer RD I/O Control Register A1	TRDIORA1	10001000b
0152h	Timer RD I/O Control Register C1	TRDIORC1	10001000b
0153h	Timer RD Status Register 1	TRDSR1	11000000b
0154h	Timer RD Interrupt Enable Register 1	TRDIER1	11100000b
0155h	Timer RD PWM Mode Output Level Control Register 1	TRDPOCR1	11111000b
0156h	Timer RD Counter 1	TRD1	00h
0157h			00h
0158h	Timer RD General Register A1	TRDGRA1	FFh
0159h			FFh
015Ah	Timer RD General Register B1	TRDGRB1	FFh
015Bh			FFh
015Ch	Timer RD General Register C1	TRDGRC1	FFh
015Dh			FFh
015Eh	Timer RD General Register D1	TRDGRD1	FFh
015Fh			FFh
0160h	UART1 Transmit/Receive Mode Register	U1MR	00h
0161h	UART1 Bit Rate Register	U1BRG	XXh
0162h	UART1 Transmit Buffer Register	U1TB	XXh
0163h			XXh
0164h	UART1 Transmit/Receive Control Register 0	U1C0	00001000b
0165h	UART1 Transmit/Receive Control Register 1	U1C1	00000010b
0166h	UART1 Receive Buffer Register	U1RB	XXh
0167h			XXh
0168h			
0169h			
016Ah			
016Bh			
016Ch			
016Dh			
016Eh			
016Fh			
0170h	Timer RG Mode Register	TRGMR	01000000b
0171h	Timer RG Count Control Register	TRGCNTC	00h
0172h	Timer RG Control Register	TRGCR	10000000b
0173h	Timer RG Interrupt Enable Register	TRGIER	11110000b
0174h	Timer RG Status Register	TRGSR	11100000b
0175h	Timer RG I/O Control Register	TRGIOR	00h
0176h	Timer RG Counter	TRG	00h
0177h			00h
0178h	Timer RG General Register A	TRGGRA	FFh
0179h			FFh
017Ah	Timer RG General Register B	TRGGRB	FFh
017Bh			FFh
017Ch	Timer RG General Register C	TRGGRC	FFh
017Dh			FFh
017Eh	Timer RG General Register D	TRGGRD	FFh
017Fh			FFh

X: Undefined

Note:

1. The blank areas are reserved and cannot be accessed by users.

Table 5.3 A/D Converter Characteristics

Symbol	Parameter		Conditions		Standard			Unit
					Min.	Typ.	Max.	
—	Resolution		$V_{ref} = AV_{CC}$		—	—	10	Bit
—	Absolute accuracy	10-bit mode	$V_{ref} = AV_{CC} = 5.0\text{ V}$	AN0 to AN7 input, AN8 to AN11 input	—	—	± 3	LSB
			$V_{ref} = AV_{CC} = 3.3\text{ V}$	AN0 to AN7 input, AN8 to AN11 input	—	—	± 5	LSB
			$V_{ref} = AV_{CC} = 3.0\text{ V}$	AN0 to AN7 input, AN8 to AN11 input	—	—	± 5	LSB
			$V_{ref} = AV_{CC} = 2.2\text{ V}$	AN0 to AN7 input, AN8 to AN11 input	—	—	± 5	LSB
		8-bit mode	$V_{ref} = AV_{CC} = 5.0\text{ V}$	AN0 to AN7 input, AN8 to AN11 input	—	—	± 2	LSB
			$V_{ref} = AV_{CC} = 3.3\text{ V}$	AN0 to AN7 input, AN8 to AN11 input	—	—	± 2	LSB
			$V_{ref} = AV_{CC} = 3.0\text{ V}$	AN0 to AN7 input, AN8 to AN11 input	—	—	± 2	LSB
			$V_{ref} = AV_{CC} = 2.2\text{ V}$	AN0 to AN7 input, AN8 to AN11 input	—	—	± 2	LSB
ϕ_{AD}	A/D conversion clock		$4.0\text{ V} \leq V_{ref} = AV_{CC} \leq 5.5\text{ V}^{(2)}$		2	—	20	MHz
			$3.2\text{ V} \leq V_{ref} = AV_{CC} \leq 5.5\text{ V}^{(2)}$		2	—	16	MHz
			$2.7\text{ V} \leq V_{ref} = AV_{CC} \leq 5.5\text{ V}^{(2)}$		2	—	10	MHz
			$2.2\text{ V} \leq V_{ref} = AV_{CC} \leq 5.5\text{ V}^{(2)}$		2	—	5	MHz
—	Tolerance level impedance				—	3	—	$k\Omega$
t_{CONV}	Conversion time	10-bit mode	$V_{ref} = AV_{CC} = 5.0\text{ V}$, $\phi_{AD} = 20\text{ MHz}$		2.2	—	—	μs
		8-bit mode	$V_{ref} = AV_{CC} = 5.0\text{ V}$, $\phi_{AD} = 20\text{ MHz}$		2.2	—	—	μs
t_{SAMP}	Sampling time		$\phi_{AD} = 20\text{ MHz}$		0.8	—	—	μs
I_{Vref}	V_{ref} current		$V_{CC} = 5.0\text{ V}$, $XIN = f_1 = \phi_{AD} = 20\text{ MHz}$		—	45	—	μA
V_{ref}	Reference voltage				2.2	—	AV_{CC}	V
V_{IA}	Analog input voltage ⁽³⁾				0	—	V_{ref}	V
OCVREF	On-chip reference voltage		$2\text{ MHz} \leq \phi_{AD} \leq 4\text{ MHz}$		1.19	1.34	1.49	V

Notes:

- $V_{CC}/AV_{CC} = V_{ref} = 2.2$ to 5.5 V , $V_{SS} = 0\text{ V}$, and $T_{opr} = -20$ to $85\text{ }^\circ\text{C}$ (N version)/ -40 to $85\text{ }^\circ\text{C}$ (D version), unless otherwise specified.
- The A/D conversion result will be undefined in wait mode, stop mode, when the flash memory stops, and in low-current-consumption mode. Do not perform A/D conversion in these states or transition to these states during A/D conversion.
- When the analog input voltage is over the reference voltage, the A/D conversion result will be 3FFh in 10-bit mode and FFh in 8-bit mode.

Table 5.4 D/A Converter Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
—	Resolution		—	—	8	Bit
—	Absolute accuracy		—	—	2.5	LSB
t_{su}	Setup time		—	—	3	μs
R_o	Output resistor		—	6	—	$k\Omega$
I_{Vref}	Reference power input current	(Note 2)	—	—	1.5	mA

Notes:

- $V_{CC}/AV_{CC} = V_{ref} = 2.7$ to 5.5 V and $T_{opr} = -20$ to 85 °C (N version)/ -40 to 85 °C (D version), unless otherwise specified.
- This applies when one D/A converter is used and the value of the DA_i register ($i = 0$ or 1) for the unused D/A converter is 00h. The resistor ladder of the A/D converter is not included.

Table 5.5 Comparator B Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V_{ref}	IVREF1, IVREF3 input reference voltage		0	—	$V_{CC} - 1.4$	V
V_i	IVCMP1, IVCMP3 input voltage		-0.3	—	$V_{CC} + 0.3$	V
—	Offset		—	5	100	mV
t_d	Comparator output delay time ⁽²⁾	$V_i = V_{ref} \pm 100$ mV	—	0.1	—	μs
I_{CMP}	Comparator operating current	$V_{CC} = 5.0$ V	—	17.5	—	μA

Notes:

- $V_{CC} = 2.7$ to 5.5 V and $T_{opr} = -20$ to 85 °C (N version)/ -40 to 85 °C (D version), unless otherwise specified.
- When the digital filter is disabled.

Table 5.15 Timing Requirements of Synchronous Serial Communication Unit (SSU)

Symbol	Parameter		Conditions	Standard			Unit
				Min.	Typ.	Max.	
tsucyc	SSCK clock cycle time			4	—	—	tcyc (2)
tHI	SSCK clock "H" width			0.4	—	0.6	tsucyc
tLO	SSCK clock "L" width			0.4	—	0.6	tsucyc
tRISE	SSCK clock rising time	Master		—	—	1	tcyc (2)
		Slave		—	—	1	μs
tFALL	SSCK clock falling time	Master		—	—	1	tcyc (2)
		Slave		—	—	1	μs
tsu	SSO, SSI data input setup time			100	—	—	ns
tH	SSO, SSI data input hold time			1	—	—	tcyc (2)
tLEAD	SCS setup time	Slave		1tcyc + 50	—	—	ns
tLAG	SCS hold time	Slave		1tcyc + 50	—	—	ns
tOD	SSO, SSI data output delay time			—	—	1	tcyc (2)
tSA	SSI slave access time		2.7 V ≤ Vcc ≤ 5.5 V	—	—	1.5tcyc + 100	ns
			1.8 V ≤ Vcc < 2.7 V	—	—	1.5tcyc + 200	ns
tOR	SSI slave out open time		2.7 V ≤ Vcc ≤ 5.5 V	—	—	1.5tcyc + 100	ns
			1.8 V ≤ Vcc < 2.7 V	—	—	1.5tcyc + 200	ns

Notes:

1. Vcc = 1.8 to 5.5 V, Vss = 0 V, and Topr = -20 to 85 °C (N version)/-40 to 85 °C (D version), unless otherwise specified.
2. 1tcyc = 1/f1(s)

Table 5.17 Electrical Characteristics (1) [4.2 V ≤ Vcc ≤ 5.5 V]

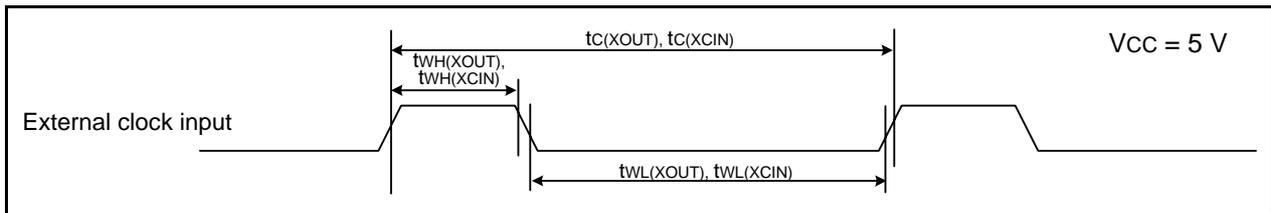
Symbol	Parameter		Condition		Standard			Unit
					Min.	Typ.	Max.	
VOH	Output "H" voltage	Other than XOUT	Drive capacity High Vcc = 5 V	IOH = -20 mA	Vcc - 2.0	—	Vcc	V
			Drive capacity Low Vcc = 5 V	IOH = -5 mA	Vcc - 2.0	—	Vcc	V
		XOUT	Vcc = 5 V	IOH = -200 μA	1.0	—	Vcc	V
VOL	Output "L" voltage	Other than XOUT	Drive capacity High Vcc = 5 V	IOl = 20 mA	—	—	2.0	V
			Drive capacity Low Vcc = 5 V	IOl = 5 mA	—	—	2.0	V
		XOUT	Vcc = 5 V	IOl = 200 μA	—	—	0.5	V
VT+-VT-	Hysteresis	INT0, INT1, INT2, INT3, INT4, KI0, KI1, KI2, KI3, TRAIO, TRBO, TRCIOA, TRCIOB, TRCIOC, TRCIOD, TRDIOA0, TRDIOB0, TRDIOC0, TRDIOD0, TRDIOA1, TRDIOB1, TRDIOC1, TRDIOD1, TRCTRG, TRCCLK, TRFI, TRGIOA, TRGIOB, ADTRG, RXD0, RXD1, RXD2, CLK0, CLK1, CLK2, SSI, SCL, SDA, SSO			0.1	1.2	—	V
		RESET			0.1	1.2	—	V
IiH	Input "H" current		Vi = 5 V, Vcc = 5.0 V		—	—	5.0	μA
IiL	Input "L" current		Vi = 0 V, Vcc = 5.0 V		—	—	-5.0	μA
RPULLUP	Pull-up resistance		Vi = 0 V, Vcc = 5.0 V		25	50	100	kΩ
RfXIN	Feedback resistance	XIN			—	0.3	—	MΩ
RfXCIN	Feedback resistance	XCIN			—	8	—	MΩ
V _{RAM}	RAM hold voltage		During stop mode		1.8	—	—	V

Note:

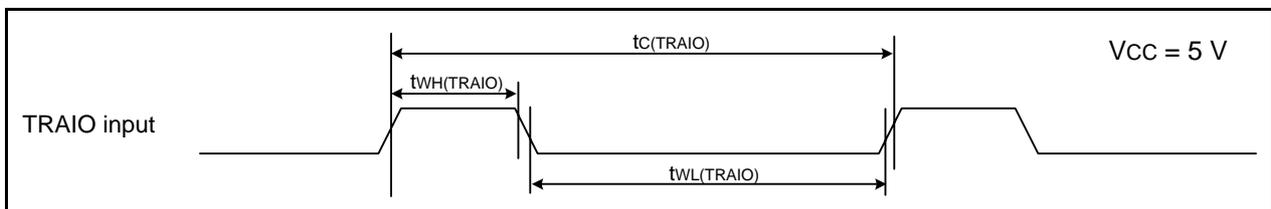
- 4.2 V ≤ Vcc ≤ 5.5 V, T_{opr} = -20 to 85 °C (N version)/-40 to 85 °C (D version), and f(XIN) = 20 MHz, unless otherwise specified.

Timing Requirements (Unless Otherwise Specified: $V_{CC} = 5\text{ V}$, $V_{SS} = 0\text{ V}$, $T_{opr} = 25\text{ }^{\circ}\text{C}$)**Table 5.19 External Clock Input (XOUT, XCIN)**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_c(\text{XOUT})$	XOUT input cycle time	50	—	ns
$t_{WH}(\text{XOUT})$	XOUT input "H" width	24	—	ns
$t_{WL}(\text{XOUT})$	XOUT input "L" width	24	—	ns
$t_c(\text{XCIN})$	XCIN input cycle time	14	—	μs
$t_{WH}(\text{XCIN})$	XCIN input "H" width	7	—	μs
$t_{WL}(\text{XCIN})$	XCIN input "L" width	7	—	μs

**Figure 5.8 External Clock Input Timing Diagram when $V_{CC} = 5\text{ V}$** **Table 5.20 TRAIO Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_c(\text{TRAIO})$	TRAIO input cycle time	100	—	ns
$t_{WH}(\text{TRAIO})$	TRAIO input "H" width	40	—	ns
$t_{WL}(\text{TRAIO})$	TRAIO input "L" width	40	—	ns

**Figure 5.9 TRAIO Input Timing Diagram when $V_{CC} = 5\text{ V}$** **Table 5.21 TRFI Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_c(\text{TRFI})$	TRFI input cycle time	400 (1)	—	ns
$t_{WH}(\text{TRFI})$	TRFI input "H" width	200 (2)	—	ns
$t_{WL}(\text{TRFI})$	TRFI input "L" width	200 (2)	—	ns

Notes:

1. When using timer RF input capture mode, adjust the cycle time to $(1/\text{timer RF count source frequency} \times 3)$ or above.
2. When using timer RF input capture mode, adjust the pulse width to $(1/\text{timer RF count source frequency} \times 1.5)$ or above.

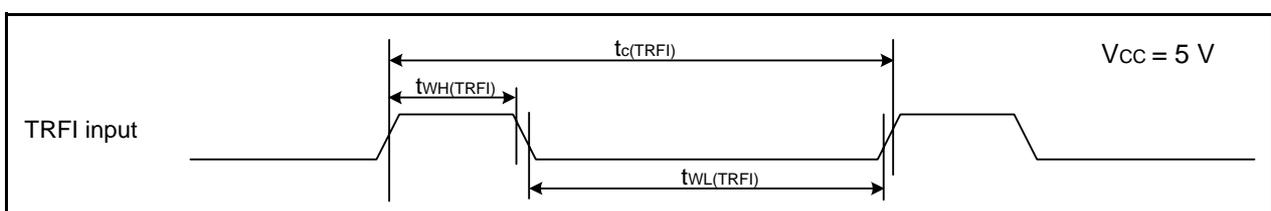
**Figure 5.10 TRFI Input Timing Diagram when $V_{CC} = 5\text{ V}$**

Table 5.24 Electrical Characteristics (3) [2.7 V ≤ V_{CC} < 4.2 V]

Symbol	Parameter		Condition	Standard			Unit	
				Min.	Typ.	Max.		
V _{OH}	Output "H" voltage	Other than XOUT	Drive capacity High	I _{OH} = -5 mA	V _{CC} - 0.5	—	V _{CC}	V
			Drive capacity Low	I _{OH} = -1 mA	V _{CC} - 0.5	—	V _{CC}	V
		XOUT	I _{OH} = -200 μA	1.0	—	V _{CC}	V	
V _{OL}	Output "L" voltage	Other than XOUT	Drive capacity High	I _{OL} = 5 mA	—	—	0.5	V
			Drive capacity Low	I _{OL} = 1 mA	—	—	0.5	V
		XOUT	I _{OL} = 200 μA	—	—	0.5	V	
V _{T+} -V _{T-}	Hysteresis	INT0, INT1, INT2, INT3, INT4, KI0, KI1, KI2, KI3, TRAIO, TRBO, TRCIOA, TRCIOB, TRCIOC, TRCIOD, TRDIOA0, TRDIOB0, TRDIOC0, TRDIOD0, TRDIOA1, TRDIOB1, TRDIOC1, TRDIOD1, TRCTRG, TRCCLK, TRFI, TRGIOA, TRGIOB, ADTRG, RXD0, RXD1, RXD2, CLK0, CLK1, CLK2, SSI, SCL, SDA, SSO	V _{CC} = 3.0 V	0.1	0.4	—	V	
		RESET	V _{CC} = 3.0 V	0.1	0.5	—	V	
I _{IH}	Input "H" current		V _I = 3 V, V _{CC} = 3.0 V		—	—	4.0	μA
I _{IL}	Input "L" current		V _I = 0 V, V _{CC} = 3.0 V		—	—	-4.0	μA
R _{PULLUP}	Pull-up resistance		V _I = 0 V, V _{CC} = 3.0 V		42	84	168	kΩ
R _{iXIN}	Feedback resistance	XIN			—	0.3	—	MΩ
R _{iXCIN}	Feedback resistance	XCIN			—	8	—	MΩ
V _{RAM}	RAM hold voltage		During stop mode		1.8	—	—	V

Note:

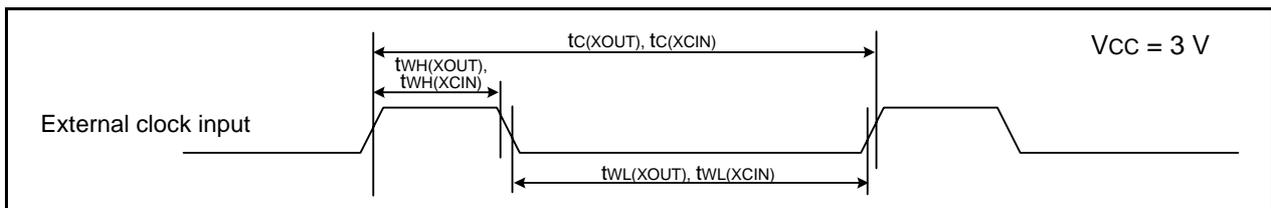
- 2.7 V ≤ V_{CC} < 4.2 V, T_{opr} = -20 to 85 °C (N version)/-40 to 85 °C (D version), and f(XIN) = 10 MHz, unless otherwise specified.

**Table 5.25 Electrical Characteristics (4) [2.7 V ≤ Vcc ≤ 3.3 V]
(T_{opr} = -20 to 85 °C (N version)/-40 to 85 °C (D version), unless otherwise specified.)**

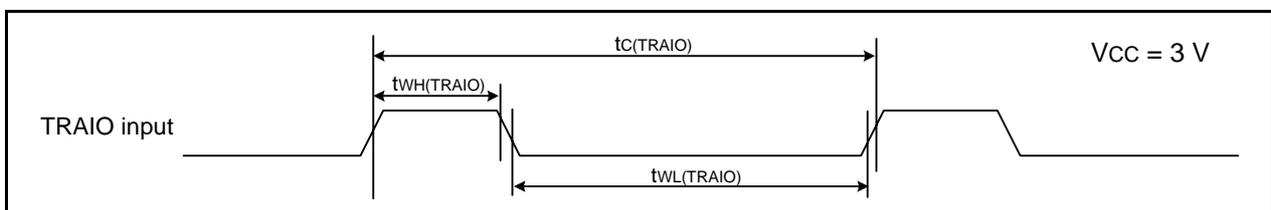
Symbol	Parameter	Condition	Standard			Unit	
			Min.	Typ.	Max.		
I _{cc}	Power supply current (V _{cc} = 2.7 to 3.3 V) Single-chip mode, output pins are open, other pins are V _{ss}	High-speed clock mode	XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	—	3.5	10	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	—	1.5	7.5	mA
		High-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator on f _{OCO-F} = 20 MHz Low-speed on-chip oscillator on = 125 kHz No division	—	7.0	15	mA
			XIN clock off High-speed on-chip oscillator on f _{OCO-F} = 20 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-8	—	3.0	—	mA
			XIN clock off High-speed on-chip oscillator on f _{OCO-F} = 10 MHz Low-speed on-chip oscillator on = 125 kHz No division	—	4.0	—	mA
			XIN clock off High-speed on-chip oscillator on f _{OCO-F} = 10 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-8	—	1.5	—	mA
			XIN clock off High-speed on-chip oscillator on f _{OCO-F} = 4 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-16, MSTIIC = MSTTRD = MSTTRC = 1	—	1	—	mA
		Low-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8, FMR27 = 1, VCA20 = 0	—	90	390	μA
		Low-speed clock mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz No division FMR27 = 1, VCA20 = 0	—	80	400	μA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz No division Program operation on RAM Flash memory off, FMSTP = 1, VCA20 = 0	—	40	—	μA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz (peripheral clock off) While a WAIT instruction is executed VCA27 = VCA26 = VCA25 = 0, VCA20 = 1	—	3.5	—	μA
		Wait mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock operation VCA27 = VCA26 = VCA25 = 0, VCA20 = 1	—	15	90	μA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock off VCA27 = VCA26 = VCA25 = 0, VCA20 = 1	—	4	80	μA
			XIN clock off, T _{opr} = 25 °C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = VCA25 = 0	—	2.0	5.0	μA
		Stop mode	XIN clock off, T _{opr} = 85 °C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = VCA25 = 0	—	15	—	μA

Timing requirements (Unless Otherwise Specified: $V_{CC} = 3\text{ V}$, $V_{SS} = 0\text{ V}$, $T_{opr} = 25\text{ }^{\circ}\text{C}$)**Table 5.26 External Clock Input (XOUT, XCIN)**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_c(\text{XOUT})$	XOUT input cycle time	50	—	ns
$t_{WH}(\text{XOUT})$	XOUT input "H" width	24	—	ns
$t_{WL}(\text{XOUT})$	XOUT input "L" width	24	—	ns
$t_c(\text{XCIN})$	XCIN input cycle time	14	—	μs
$t_{WH}(\text{XCIN})$	XCIN input "H" width	7	—	μs
$t_{WL}(\text{XCIN})$	XCIN input "L" width	7	—	μs

**Figure 5.13 External Clock Input Timing Diagram when $V_{CC} = 3\text{ V}$** **Table 5.27 TRAI0 Input**

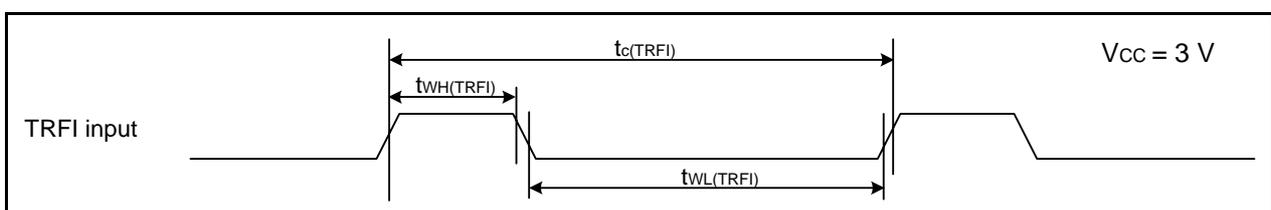
Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_c(\text{TRAIO})$	TRAIO input cycle time	300	—	ns
$t_{WH}(\text{TRAIO})$	TRAIO input "H" width	120	—	ns
$t_{WL}(\text{TRAIO})$	TRAIO input "L" width	120	—	ns

**Figure 5.14 TRAI0 Input Timing Diagram when $V_{CC} = 3\text{ V}$** **Table 5.28 TRFI Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_c(\text{TRFI})$	TRFI input cycle time	1200 (1)	—	ns
$t_{WH}(\text{TRFI})$	TRFI input "H" width	600 (2)	—	ns
$t_{WL}(\text{TRFI})$	TRFI input "L" width	600 (2)	—	ns

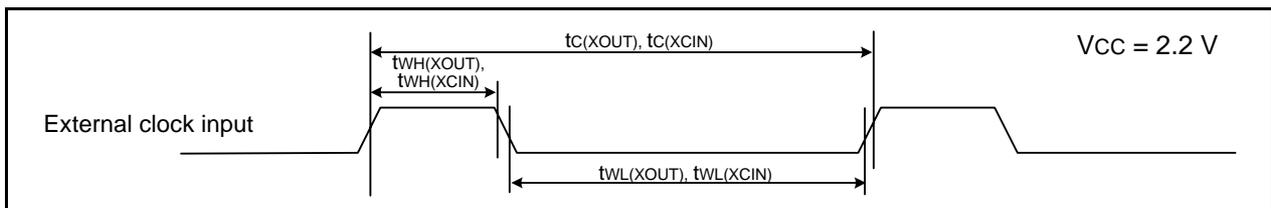
Notes:

1. When using timer RF input capture mode, adjust the cycle time to $(1/\text{timer RF count source frequency} \times 3)$ or above.
2. When using timer RF input capture mode, adjust the pulse width to $(1/\text{timer RF count source frequency} \times 1.5)$ or above.

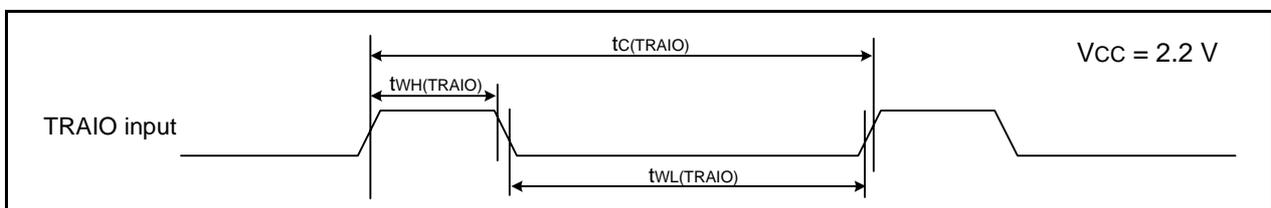
**Figure 5.15 TRFI Input Timing Diagram when $V_{CC} = 3\text{ V}$**

Timing requirements (Unless Otherwise Specified: $V_{CC} = 2.2\text{ V}$, $V_{SS} = 0\text{ V}$, $T_{opr} = 25\text{ }^{\circ}\text{C}$)**Table 5.33 External Clock Input (XOUT, XCIN)**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(XOUT)}$	XOUT input cycle time	200	—	ns
$t_{WH(XOUT)}$	XOUT input "H" width	90	—	ns
$t_{WL(XOUT)}$	XOUT input "L" width	90	—	ns
$t_{c(XCIN)}$	XCIN input cycle time	14	—	μs
$t_{WH(XCIN)}$	XCIN input "H" width	7	—	μs
$t_{WL(XCIN)}$	XCIN input "L" width	7	—	μs

**Figure 5.18 External Clock Input Timing Diagram when $V_{CC} = 2.2\text{ V}$** **Table 5.34 TRAI0 Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRAIO)}$	TRAIO input cycle time	500	—	ns
$t_{WH(TRAIO)}$	TRAIO input "H" width	200	—	ns
$t_{WL(TRAIO)}$	TRAIO input "L" width	200	—	ns

**Figure 5.19 TRAI0 Input Timing Diagram when $V_{CC} = 2.2\text{ V}$** **Table 5.35 TRFI Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRFI)}$	TRFI input cycle time	2000 (1)	—	ns
$t_{WH(TRFI)}$	TRFI input "H" width	1000 (2)	—	ns
$t_{WL(TRFI)}$	TRFI input "L" width	1000 (2)	—	ns

Notes:

1. When using timer RF input capture mode, adjust the cycle time to $(1/\text{timer RF count source frequency} \times 3)$ or above.
2. When using timer RF input capture mode, adjust the pulse width to $(1/\text{timer RF count source frequency} \times 1.5)$ or above.

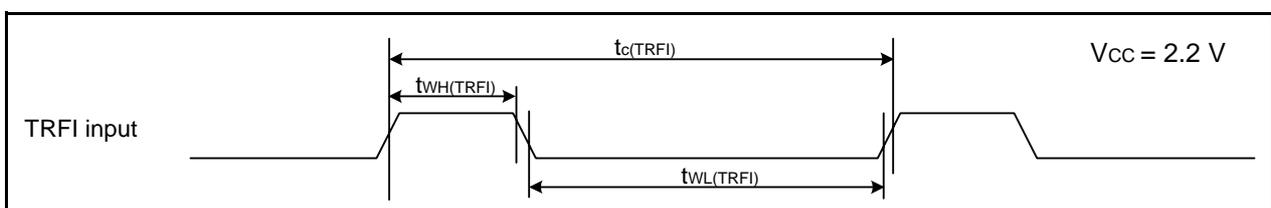
**Figure 5.20 TRFI Input Timing Diagram when $V_{CC} = 2.2\text{ V}$**

Table 5.36 Serial Interface

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLKi input cycle time	800	—	ns
$t_{w(CKH)}$	CLKi input "H" width	400	—	ns
$t_{w(CKL)}$	CLKi input "L" width	400	—	ns
$t_{d(C-Q)}$	TXDi output delay time	—	200	ns
$t_{h(C-Q)}$	TXDi hold time	0	—	ns
$t_{su(D-C)}$	RXDi input setup time	150	—	ns
$t_{h(C-D)}$	RXDi input hold time	90	—	ns

$i = 0$ to 2

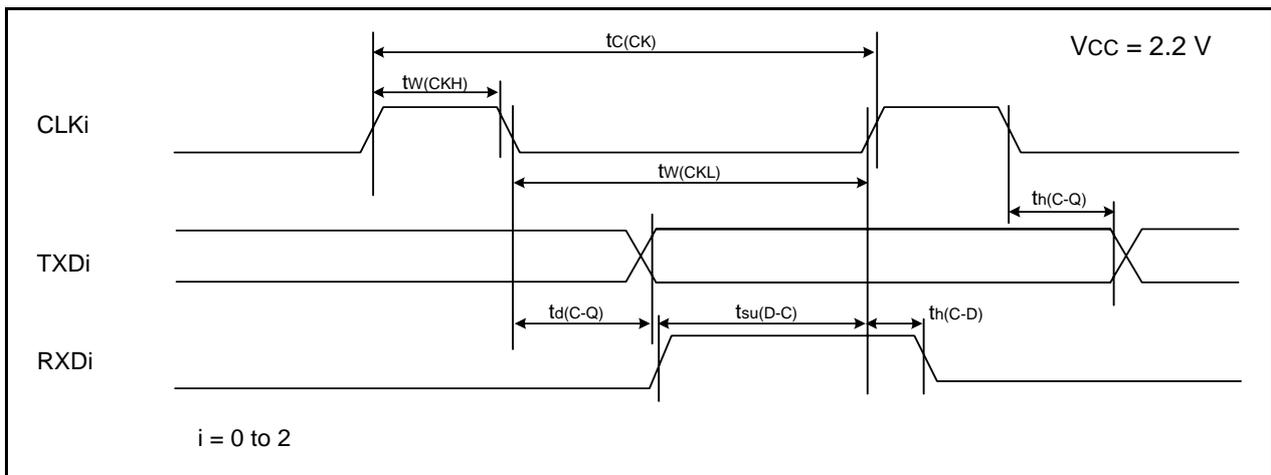


Figure 5.21 Serial Interface Timing Diagram when Vcc = 2.2 V

Table 5.37 External Interrupt \overline{INTi} ($i = 0$ to 4) Input, Key Input Interrupt \overline{Kli} ($i = 0$ to 3)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(INH)}$	\overline{INTi} input "H" width, \overline{Kli} input "H" width	1000 (1)	—	ns
$t_{w(INL)}$	\overline{INTi} input "L" width, \overline{Kli} input "L" width	1000 (2)	—	ns

Notes:

1. When selecting the digital filter by the \overline{INTi} input filter select bit, use an \overline{INTi} input HIGH width of either (1/digital filter clock frequency $\times 3$) or the minimum value of standard, whichever is greater.
2. When selecting the digital filter by the \overline{INTi} input filter select bit, use an \overline{INTi} input LOW width of either (1/digital filter clock frequency $\times 3$) or the minimum value of standard, whichever is greater.

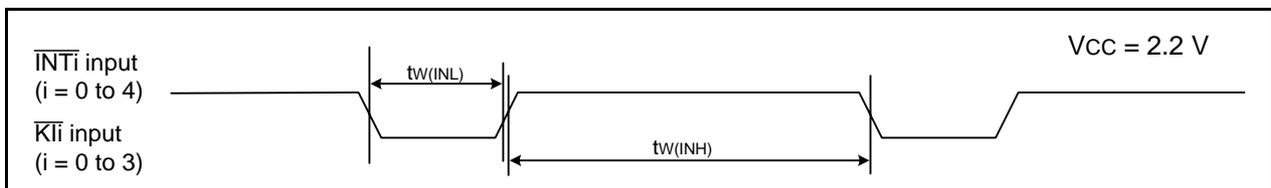
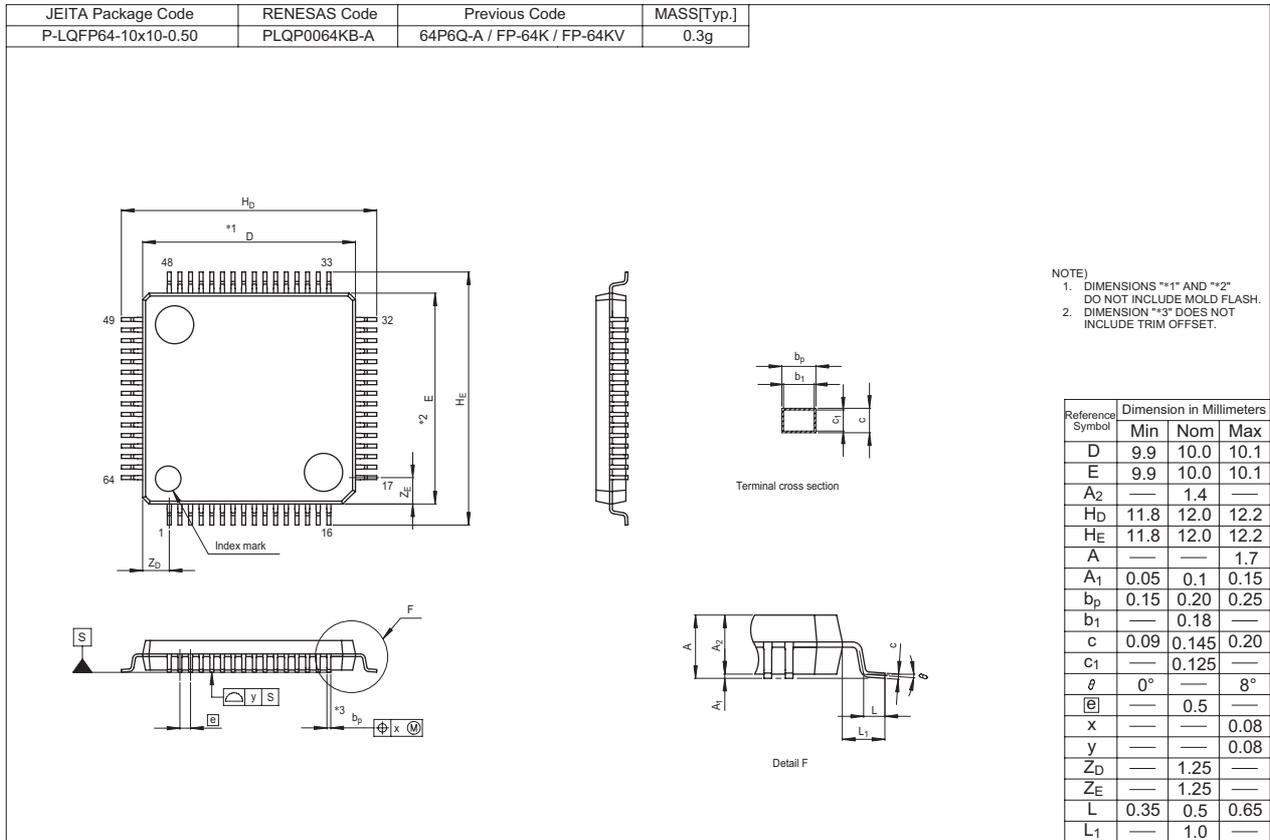
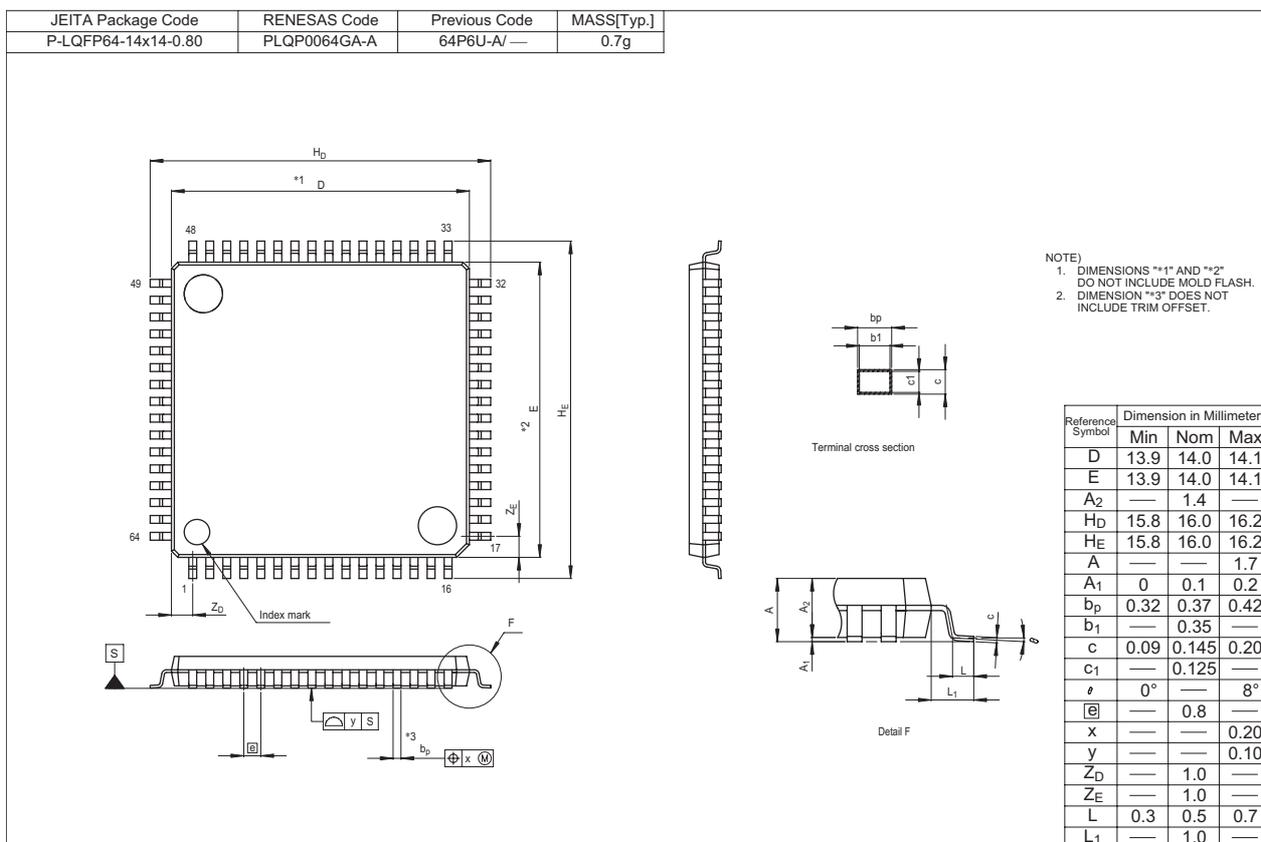


Figure 5.22 Input Timing Diagram for External Interrupt \overline{INTi} and Key Input Interrupt \overline{Kli} when Vcc = 2.2 V

Package Dimensions

Diagrams showing the latest package dimensions and mounting information are available in the “Packages” section of the Renesas Electronics website.





General Precautions in the Handling of MPU/MCU Products

The following usage notes are applicable to all MPU/MCU products from Renesas. For detailed usage notes on the products covered by this manual, refer to the relevant sections of the manual. If the descriptions under General Precautions in the Handling of MPU/MCU Products and in the body of the manual differ from each other, the description in the body of the manual takes precedence.

1. Handling of Unused Pins

Handle unused pins in accord with the directions given under Handling of Unused Pins in the manual.

- The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

2. Processing at Power-on

The state of the product is undefined at the moment when power is supplied.

- The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.

In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.

In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

3. Prohibition of Access to Reserved Addresses

Access to reserved addresses is prohibited.

- The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

4. Clock Signals

After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

- When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

5. Differences between Products

Before changing from one product to another, i.e. to one with a different part number, confirm that the change will not lead to problems.

- The characteristics of MPU/MCU in the same group but having different part numbers may differ because of the differences in internal memory capacity and layout pattern. When changing to products of different part numbers, implement a system-evaluation test for each of the products.